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(54) Title: CARRYING DEVICE OF SEMICONDUCTOR HEAT TREATMENT APPARATUS, AND SEMICONDUCTOR HEAT TREATMENT APPARATUS

(54) 发明名称: 半导体热处理设备的承载装置及半导体热处理设备

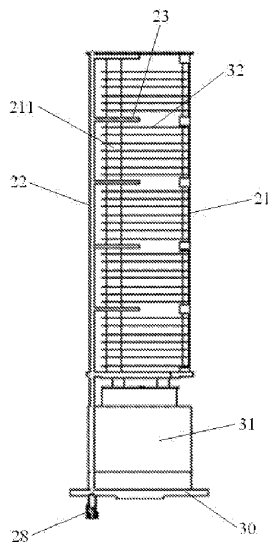


图 2

(57) Abstract: The present invention provides a carrying device of a semiconductor heat treatment apparatus, and a semiconductor heat treatment apparatus. The carrying device comprises a carrying body, the carrying body comprises a plurality of carrying positions for carrying wafers, and the plurality of carrying positions are spaced apart from each other along the axial direction of the carrying body. The carrying device further comprises a temperature measuring device, and the temperature measuring device comprises a support member and a plurality of temperature measuring assemblies, wherein the support member is connected to the carrying body and located on the outer side of the edges of the carrying positions of the carrying body; the plurality of temperature measuring assemblies are all arranged on the support member and spaced apart from each other along the axial direction of the carrying body, and each temperature measuring assembly has a temperature measuring end extending to the inner side of the edge of the corresponding carrying position, so as to measure the temperature of an area corresponding to the temperature measuring end. According to the carrying device of a semiconductor heat treatment apparatus, and the semiconductor heat treatment apparatus provided in the present invention, the accuracy of temperature measuring for a wafer can be improved.

(57) 摘要: 本发明提供一种半导体热处理设备的承载装置及半导体热处理设备, 该承载装置包括承载主体, 该承载主体包括多个用于承载晶圆的承载位, 且多个承载位沿承载主体的轴向间隔排布, 还包括测温装置, 测温装置包括支撑件和多个测温组件, 其中, 支撑件与承载主体连接, 且位于承载主体的承载位的边缘外侧; 多个测温组件均设置在支撑件上, 且沿承载主体的轴向间隔排布, 并且每个测温组件均具有延伸至承载位的边缘内侧的测温端, 用于对该测温端对应的分区的温度进行检测。本发明提供的半导体热处理设备的承载装置及半导体热处理设备, 能够提高对晶圆测温的准确性。

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